

# 玻璃載板 切割設備

製程名稱：Laser Cutting

應用於半導體與面板之玻璃、ABF複合材料  
之開槽、改質、裂片

## 設備特色

- 半導體與面板之玻璃、ABF複合材料之開槽、改質、裂片
- 製程精度:  $\pm 10 \mu\text{m}$
- 直線加工速度 250 mm/s

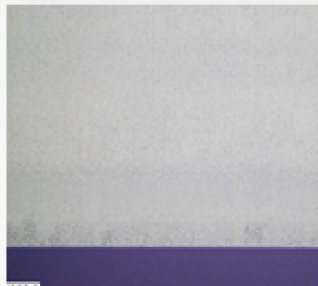
## Technological Edge

### ■ Free Shaping



### ■ Cutting Edge

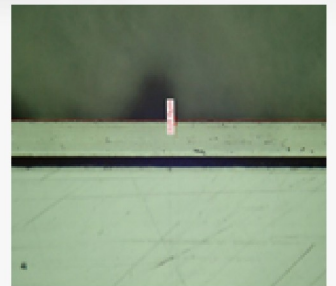
RA 0.13  $\mu\text{m}$



### ■ HAZ <math>< 5 \mu\text{m}</math>



### ■ Chipping <math>< 5 \mu\text{m}</math>



Specifications / Model		GLCM-300*300	GLCM-600*600
Machine Size	Dimensions(W*L*H)	1900*2100*2500 mm	2400*2600*2500 mm
	Weight	5,000 kg	15,000 kg
Equipment Capability	Automation	Fully-automated	
	Product size (W*L)	300*300 mm	600*600 mm
	Alignment accuracy	$\pm 5 \mu\text{m}$	
Additional Systems	Power meter	●	
	Galvo scanner system	(optional)	
	Dust collection system	●	
	Height measurement	●	
	Static eliminator system	●	
Operating Conditions	Pressure source	Min. 400 kPa	
	Negative Pressure	Min. -70 kPa	
	Ambient floor vibration	VC-B	
	Temperature	$23^{\circ}\text{C} \pm 1$	
	Electrical load	3P/3W 220 VAC 60HZ : 75A	3P/3W 220 VAC 60HZ : 150A